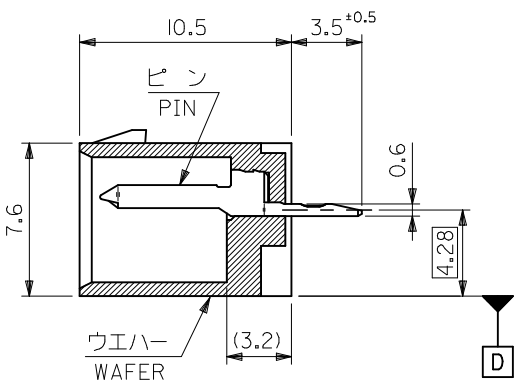
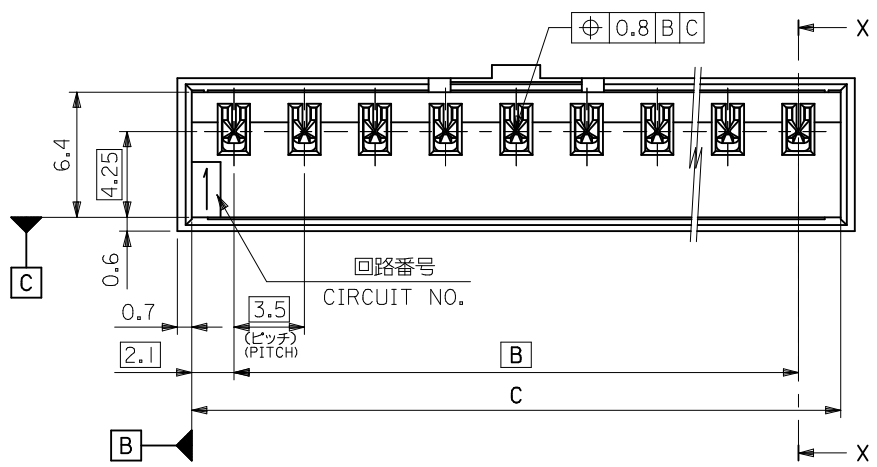


注記 NOTES

1. 嵌合相手 : 51067 シリーズ
MATE WITH : 51067 SERIES
2. 材質
MATERIAL
ウエハー : PBTP (ガラス15%入り) , UL94V-0
WAFER : PBTP (G.F 15%) , UL94V-0
ピン : 黄銅、ニッケル下地 鍍メッキ (t=0.254)
PIN : BRASS
TIN OVER NICKEL PLATING (t=0.254)
3. 本製品は 53258-**-20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53258-**-20.
4. メッキ仕様
TERMINAL PLATING
表面メッキ : スズメッキ 14μm MIN.
SURFACE PLATE : TIN 14μm MIN.
下地メッキ : ニッケルメッキ 14μm MIN.
UNDER PLATE : NICKEL 14μm MIN.

基板取付穴推奨寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)



8.7	53.2	49.0	54.6	53258-1529	15	
	49.7	45.5	51.1	-1429	14	
	46.2	42.0	47.6	-1329	13	
	42.7	38.5	44.1	-1229	12	
	39.2	35.0	40.6	-1129	11	
	35.7	31.5	37.1	-1029	10	
	32.2	28.0	33.6	-0929	9	
	28.7	24.5	30.1	-0829	8	
	25.2	21.0	26.6	-0729	7	
	21.7	17.5	23.1	-0629	6	
	18.2	14.0	19.6	-0529	5	
	8.7	14.7	10.5	16.1	-0429	4
	6.1	11.2	7.0	12.6	-0329	3
	6.1	7.7	3.5	9.1	53258-0229	2
(D)	C	B	A	MATERIAL NO.	CKT. 極致	

MATERIAL 材料
注記参照
SEE NOTES

REVISED	DESCRIPTION
EC NO: J2007-0432	2006/08/11
DRW:KSAI/T001	2006/08/21
CHKD:THARUYAMA	2006/08/21
APPR:NUKITA	2006/08/23
REV	DESCRIPTION
A	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
T. UENO	2004/04/22
CHECKED BY	DATE
M. SASAO	2004/04/22
APPROVED BY	DATE
M. SASAO	2004/04/22
MATERIAL NO.	
SEE CHART	
SIZE	A3

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
4:1	METRIC	⊙ □	
TITLE			
3.5 WIRE TO BOARD CONN -LEAD FREE-			
MOLEX MOLEX INCORPORATED			
DOCUMENT NO.		SHEET NO.	
SD-53258-005		1 OF 1	
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